



Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	I_D
30V	1.5m Ω @10V	130A
	3.0m Ω @4.5V	

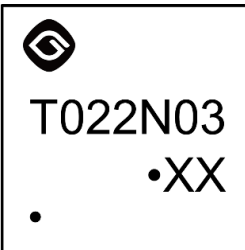
Feature

- Split Gate Trench technology
- Excellent gate charge $\times R_{DS(on)}$ product
- Excellent package for good heat dissipation

Application

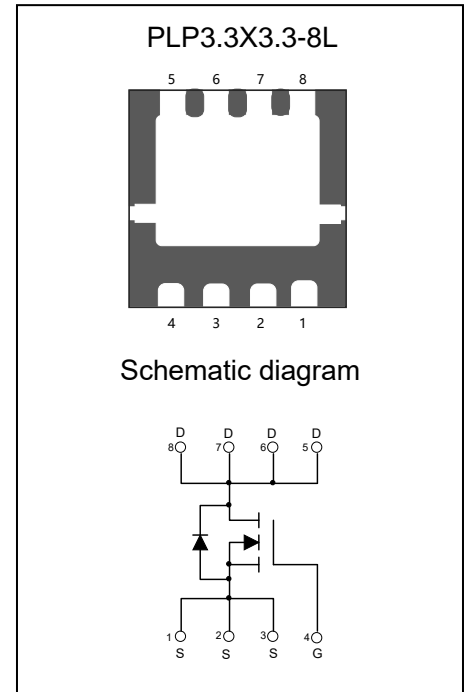
- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

MARKING:



T022N03 = Device code

XX = Date Code



ABSOLUTE MAXIMUM RATINGS ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ⁴	I_D	130	A
Pulsed Drain Current ³	I_{DM}	520	A
Avalanche Current ¹	I_{AS}	27	A
Single Pulse Avalanche Energy ¹	E_{AS}	182	mJ
Power Dissipation ²	P_D	71	W
Thermal Resistance from Junction to Case	$R_{\theta JC}$	1.76	$^\circ\text{C/W}$
Steady-State			
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~+150	$^\circ\text{C}$

MOSFET ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

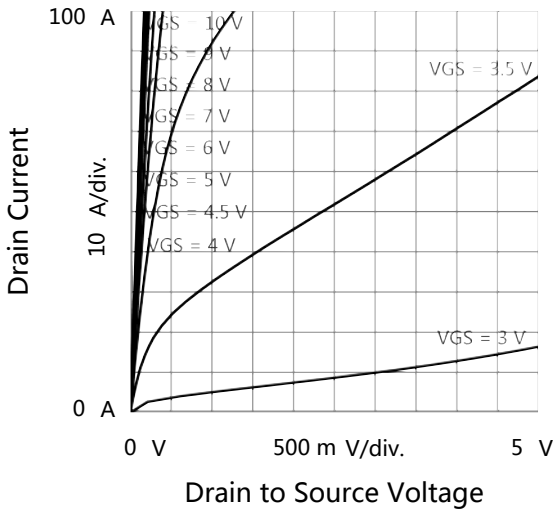
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Off Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V			±100	nA
On Characteristics⁵						
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1	2	3	V
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10V, I _D = 15A		1.5	2.2	mΩ
		V _{GS} = 4.5V, I _D = 10A		3.0	4.8	
Forward transconductance	g _{FS}	V _{DS} = 5V, I _D = 10A		30		S
Dynamic Characteristics						
Input capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz		2190		pF
Output capacitance	C _{oss}			1200		
Reverse transfer capacitance	C _{rss}			153		
Switching Characteristics						
Total gate charge	Q _g	V _{DS} = 15V, I _D = 35A, V _{GS} = 10V		39.2		nC
Gate-source charge	Q _{gs}			5.9		
Gate-drain charge	Q _{gd}			6.3		
Turn-on delay time	t _{d(on)}	V _{DD} = 15V, I _D = 35A, V _{GS} = 10V, R _G = 1.6Ω		4.9		ns
Turn-on rise time	t _r			6.9		
Turn-off delay time	t _{d(off)}			25		
Turn-off fall time	t _f			4.8		
Diode Characteristics						
Diode Forward Voltage ⁵	V _{SD}	V _{GS} = 0V, I _S = 10A		0.76	1.2	V
Maximum Diode Continuous Current ⁴	I _{SM}				300	A

Notes :

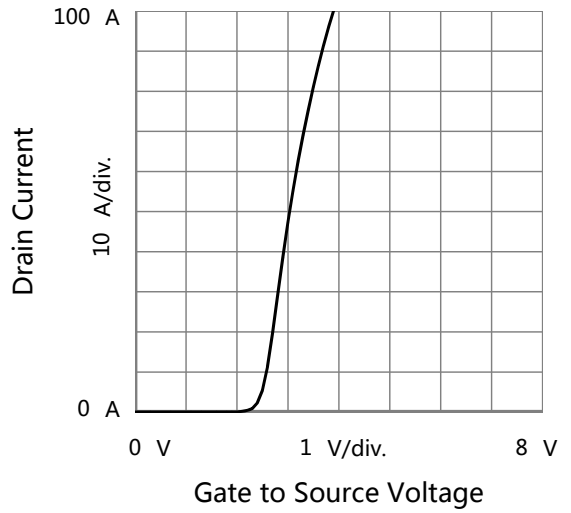
1. EAS condition: V_{DD} = 15V, V_{GS} = 10V, L = 0.5mH, R_G = 25Ω Starting T_J = 25°C.
2. The power dissipation P_D is based on T_{J(MAX)} = 150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.
3. Single pulse width limited by junction temperature T_{J(MAX)} = 150°C.
4. The maximum current rating is package limited.
5. The static characteristics are obtained using <380ms pulses, duty cycle 2% max

Typical Electrical and Thermal Characteristics

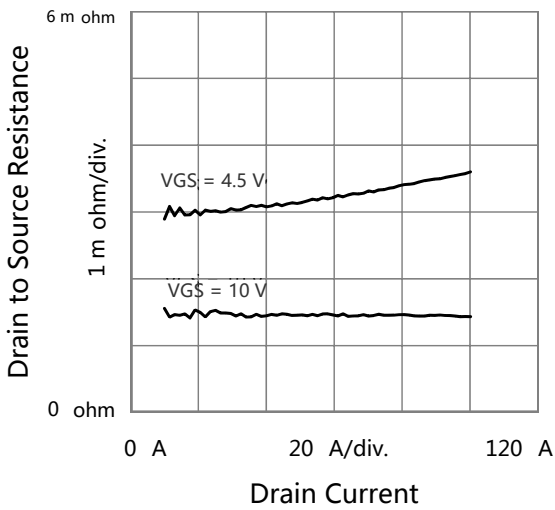
Output Characteristics



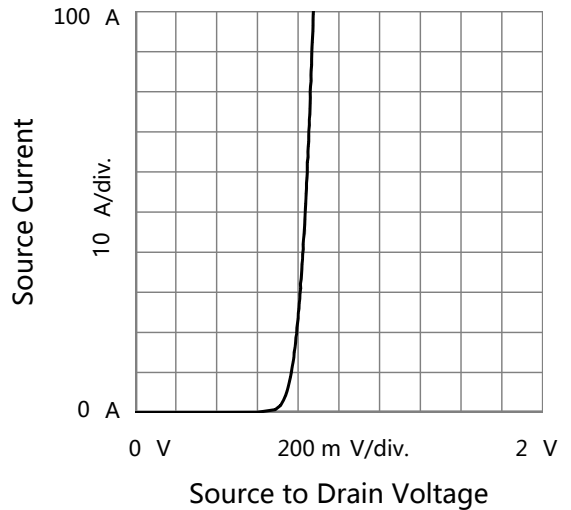
Transfer Characteristics



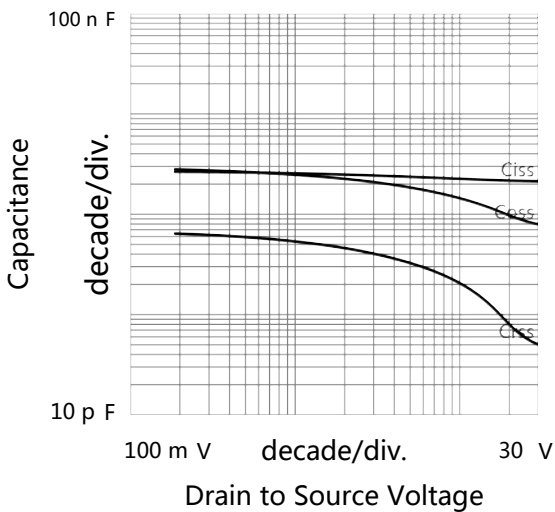
Drain to Source Resistance vs. Drain Current



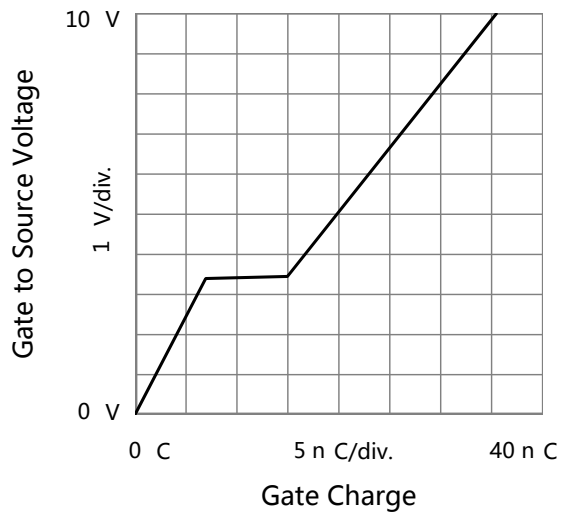
Body Diode Forward Characteristics



Capacitances

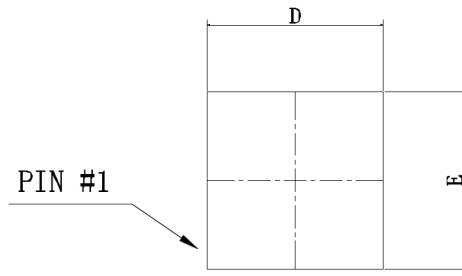


Gate Charge

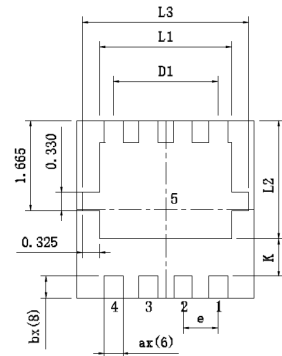


PLP3.3X3.3-8L Package Information

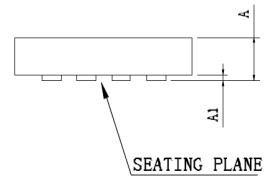
symbol	Dimension in mm		
	MIN	NOM	MAX
A	0.650	0.700	0.750
A1	0.050	0.100	0.150
D	3.200	3.300	3.400
E	3.200	3.300	3.400
D1	---	1.950	---
e	---	0.650	---
ax(6)	0.300	0.350	0.400
bx(8)	0.350	0.400	0.450
L1	2.400	2.450	2.500
L2	2.150	2.200	2.250
L3	3.050	3.100	3.150
K	0.600	0.700	0.800



Top View



Bottom View



Side View